



Material Content Data Sheet



Sales Product Name				BSC019N06NS		Issued		26. August 2018	
MA#				MA001709812					
Package				PG-TDSON-8-17		Weight*		119.40 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.188	0.99	0.99	9948	9948	
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95		
	non noble metal	iron	7439-89-6	0.038	0.03		317		
	non noble metal	copper	7440-50-8	37.762	31.63	31.67	316264	316676	
	noble metal	gold	7440-57-5	0.045	0.04	0.04	375	375	
wire	organic material	carbon black	1333-86-4	0.131	0.11		1101		
encapsulation	plastics	epoxy resin	-	5.127	4.29		42941		
	inorganic material	silicondioxide	60676-86-0	38.563	32.30	36.70	322977	367019	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12158	12158	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1386	1386	
solder	non noble metal	tin	7440-31-5	0.034	0.03		281		
	noble metal	silver	7440-22-4	0.042	0.04		351		
	non noble metal	lead	7439-92-1	1.602	1.34	1.41	13421	14053	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
heatspreader	non noble metal	zinc	7440-66-6	0.013	0.01		113		
	non noble metal	iron	7439-89-6	0.269	0.22		2250		
	non noble metal	copper	7440-50-8	10.909	9.14	9.37	91366	93757	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55		
heat sink CLIP	non noble metal	zinc	7440-66-6	0.026	0.02		222		
	non noble metal	iron	7439-89-6	0.529	0.44		4431		
	non noble metal	copper	7440-50-8	21.482	17.99	18.46	179920	184628	
	*deviation < 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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